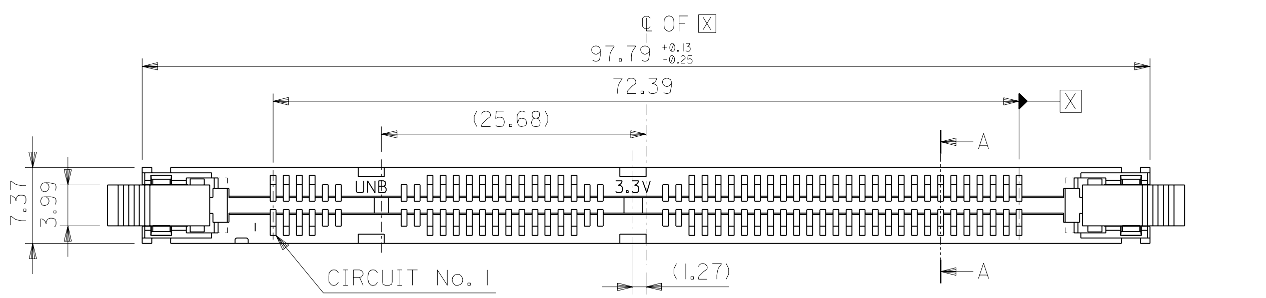
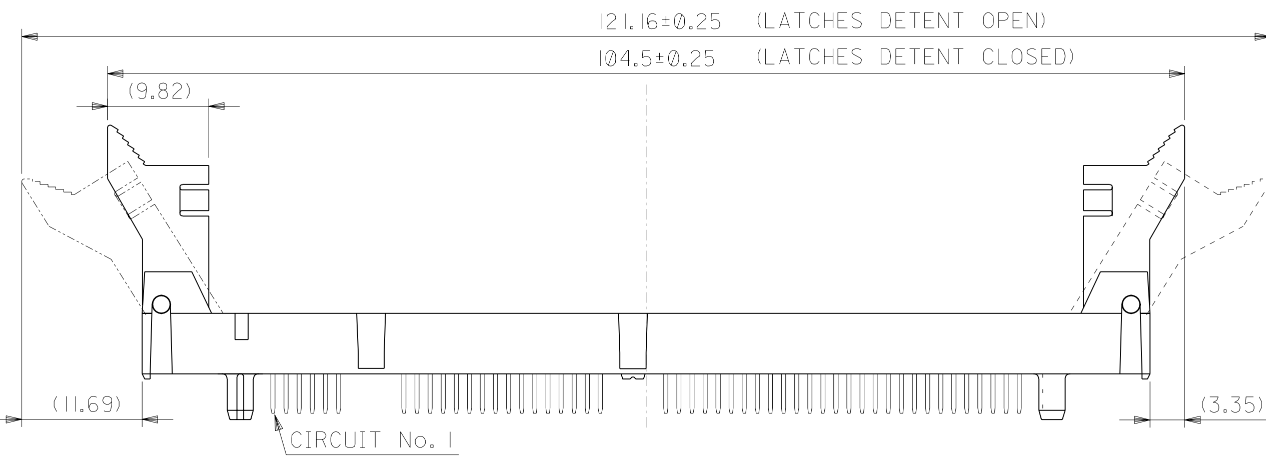
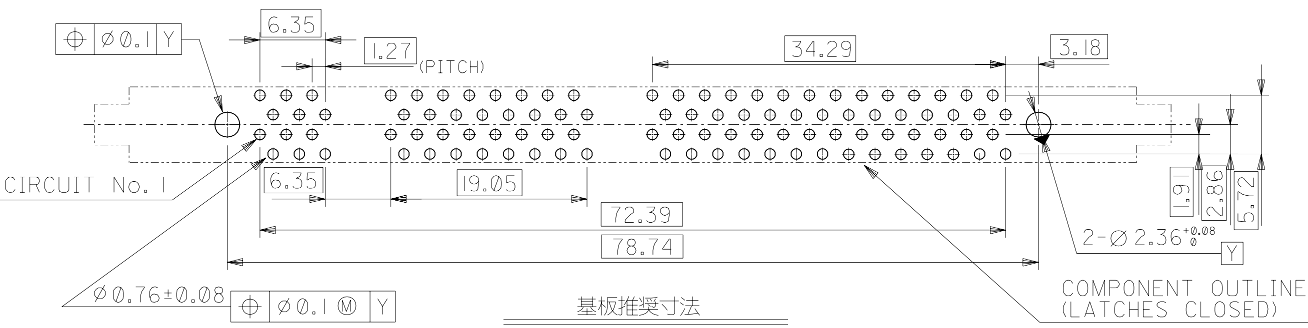
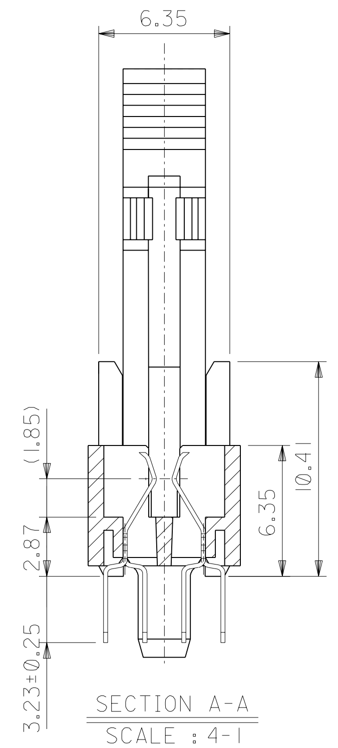
DWG. NO. SD-71251-5101







基板推奨寸法
RECOMMENDED P.C.B. LAYOUT



角度 ANGLE	±3°
30 以上 OVER	±0.3
10 以上 OVER 30 未満 UNDER	±0.25
10 未満 UNDER	±0.2
一般公差 GENERAL TOLERANCES	

記号 LTR	変更内容 REVISION RECORD	DR.	CHK.	日付 DATE
A	変更 REVISED (J2004-4509)	Y.W	M.S	'04/05/31
0	新規作成 PROPOSED (JD90709)	T.H	M.S	'98/11/12

材料 MATERIAL 注参照 SEE NOTES

仕上げ FINISH 注参照 SEE NOTES

適用電線範囲 WIRE RANGE —#—

被覆外径 INS. RANGE —#—

DRAWN BY '98/11/12 T. Hirata

CHK'D BY M. Sasao

APP'D BY [signature]

尺度 SCALE 2 - 1

molex MOLEX-JAPAN CO.,LTD. 日本モレックス株式会社

REVISE ONLY ON CAD SYSTEM

TITLE 名称
1.27 PITCH DIMM
100 CIRCUIT MULTI-KEY
HOUSING ASS'Y
-LEAD FREE-

DWG. NO. SD-71251-5101 SHEET 1 OF 2 REV A

S71251J1.DGN

:MM DIMENSIONS IN METRIC DO NOT SCALE DRAWING

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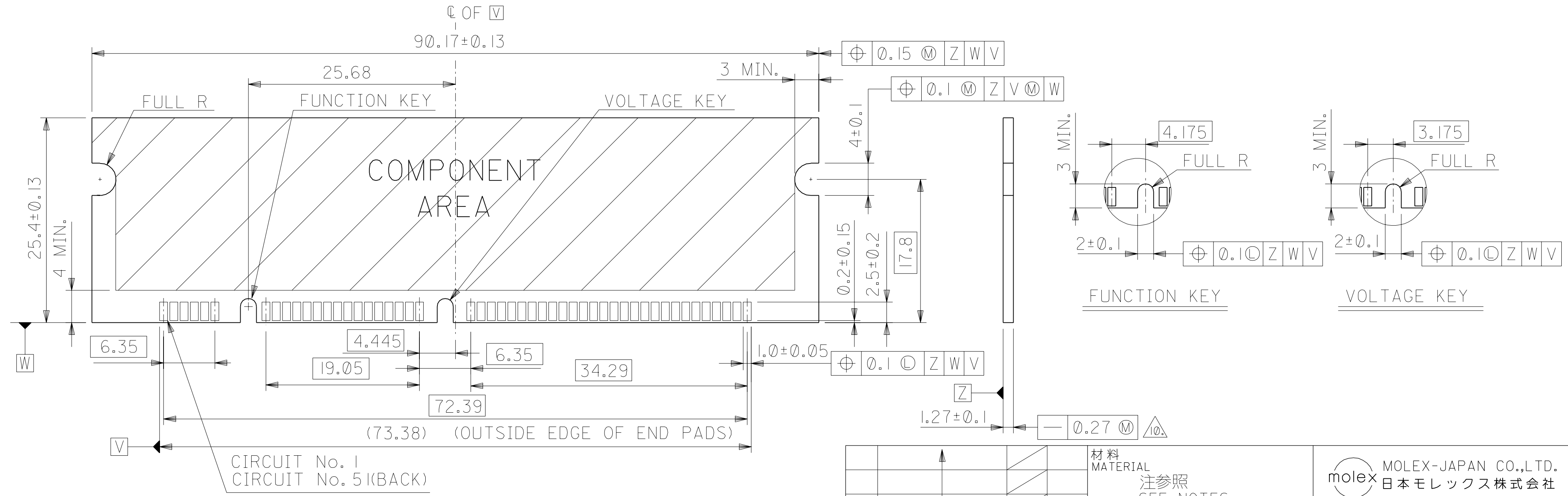
EN-01C(032)MXJ-32

DWG. NO. SD-71251-5101

注記
NOTES:

1. モジュールの推奨基板厚：1.27±0.1 （パッド含む）
CARD SLOT ACCEPTS 1.27±0.1 MODULE THICKNESS. (MEASURED OVER P.C. PADS).
2. ペグには、基板に対する挿入力が発生します。
ALL PEGS ARE INTERFERENCE FITS TO PCB UNLESS NOTED ON THE DWG.
3. 製品仕様については、PS－71251－5101 をご参照下さい。
REFER TO PRODUCT SPEC. PS-71251-5101. FOR PERFORMANCE SPECIFICATIONS.
4. 梱包形態は、トレイ梱包です。
PRODUCT IS PACKAGED IN TRAYS.
5. 推奨モジュール・レイアウトはMO－161をご参照下さい。
RECOMMENDED MODULE LAYOUT SHALL BE PER MO-161.
6. モジュール基板パッドの推奨メッキ仕様
金： 0.76MICROMETER MIN.
ニッケル下地： 2.0MICROMETER MIN.
RECOMMENDED PLATING ON MODULE PADS:
0.76MICROMETER MIN. HARD GOLD
OVER 2.0MICROMETER MIN. NICKEL.
7. 製造日コードはハウジングの側面に刻印されます。
PRODUCT WILL HAVE DATE CODE STAMPED ON SIDE OF HOUSING.
8. 材質
ハウジング：耐熱性樹脂 （黒色）
ラッチ：耐熱性樹脂 （アイボリー）
ターミナル：リン青銅
MATERIALS:
HOUSING- HIGH-TEMP THERMOPLASTIC
COLOR: BLACK
LATCHES - HIGH-TEMP THERMOPLASTIC
COLOR: IVORY
TERMINAL- PHOSPHOR BRONZE
9. メッキ仕様
接点部：金メッキ0.05-0.25MICROMETER
パラジウムニッケル下地0.76MICROMETER MIN.
半田付け部：錫メッキ 3.81MICROMETER MIN.
下地メッキ：ニッケルメッキ1.27MICROMETER MIN.
PLATING:
CONTACT AREA: GOLD 0.05-0.25MICROMETER
OVER PALLADIUM-NICKEL
SOLDER TAILS: TIN
3.81MICROMETER MIN.
UNDERPLATE: NICKEL 1.27MICROMETER MIN.
10. モジュール基板の真直度は、底辺より4mmの範囲に適用。
STRAIGHTNESS OF MODULE APPLIES TO THE AREA FROM THE BOTTOM OF THE CARD UP 4.
11. 電解メッキなどのために、パッドにタブを設ける場合は、それがコネクターのコンタクト部を損傷する原因とならないよう、ご配慮下さい。
IF TIE BARS ARE ATTACHED TO PADS, THE TIE BAR SHOULD BE ON AN INTERNAL LAYER, SO THAT THE REMNANT CANNOT CAUSE DAMAGE TO THE CONTACTS.



基板推奨寸法
RECOMMENDED P.C.B. LAYOUT

角度 ANGLE	±3°
30 以上 OVER	±0.3
10 以上 OVER 30 未満 UNDER	±0.25
10 未満 UNDER	±0.2
一般公差 GENERAL TOLERANCES	

記号 LTR	変更内容 REVISION RECORD	DR.	CHK.	日付 DATE
A				
0	SHEET 1 OF 2 参照 SEE SHEET 1 OF 2			

材料 MATERIAL 注参照 SEE NOTES
仕上げ FINISH 注参照 SEE NOTES
適用電線範囲 WIRE RANGE —#—
被覆外径 INS. RANGE —#—
DRAWN BY '98/11/12 T. Hirata
CHK'D BY M. Sasao
APP'D BY
尺度 SCALE 2 - 1

MOLEX-JAPAN CO.,LTD.
日本モレックス株式会社

REVISE ONLY ON CAD SYSTEM

TITLE 名称
1.27 PITCH DIMM
100 CIRCUIT MULTI-KEY
HOUSING ASS'Y
-LEAD FREE-

DWG. NO. SD-71251-5101
SHEET 2 OF 2
REV A

S71251J2.DGN

DIMENSIONS IN METRIC DO NOT SCALE DRAWING :MM

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EN-01C(032)MXJ-32

NOTES:

1. CARD SLOT ACCEPTS .050±.004 (1.27±0.10) MODULE THICKNESS. (MEASURED OVER P.C. PADS).
2. ALL PEGS ARE INTERFERENCE FITS TO PCB UNLESS NOTED ON THE DWG.
3. REFER TO PRODUCT SPEC. PS-71243 FOR PERFORMANCE SPECIFICATIONS.
4. PRODUCT IS PACKAGED IN TRAYS.
5. RECOMMENDED MODULE LAYOUT SHALL BE PER MO-161.
6. RECOMMENDED PLATING ON MODULE PADS: 30 MICROINCH/(0.76 MICROMETER) MINIMUM HARD GOLD (Au) OVER 79 MICROINCH/(2.0 MICROMETER) MINIMUM NICKEL (Ni).
7. PRODUCT WILL HAVE DATE CODE STAMPED ON SIDE OF HOUSING.

MATERIALS:

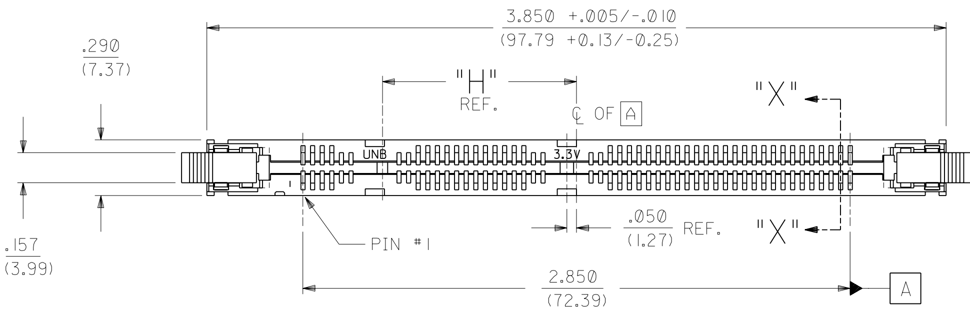
HOUSING - GLASS FILLED LIQUID CRYSTAL POLYMER (LCP), UL 94V-0, COLOR: BLACK.
TERMINAL - PHOSPHOR BRONZE
LATCHES - GLASS FILLED HIGH TEMPERATURE NYLON, UL 94V-0, COLOR: IVORY.

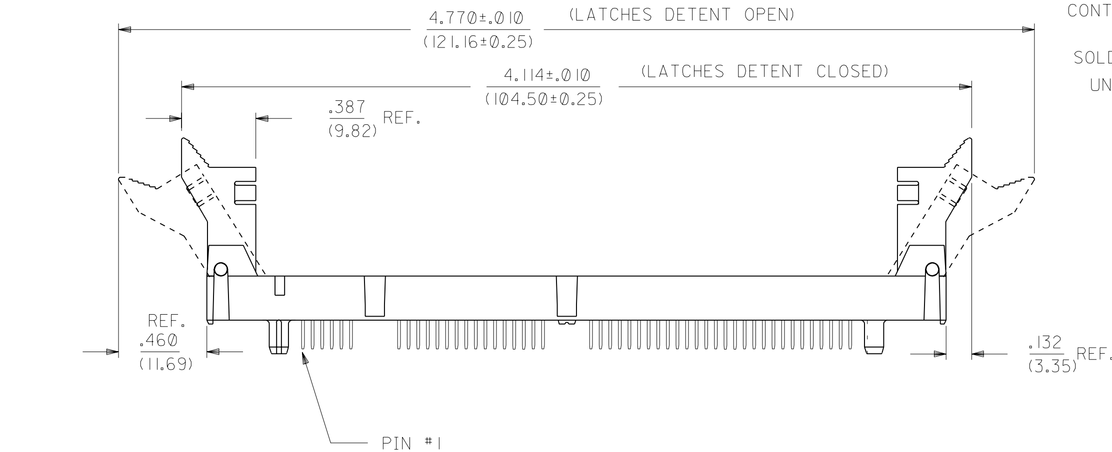
PLATING:

CONTACT AREA: MOLEX EB1 LUBRICANT OVER GOLD (Au): THICKNESS=10 MICROINCH/(0.25 MICROMETER) MINIMUM.
SOLDER TAILS: TIN (Sn): THICKNESS=150 MICROINCH/(3.81 MICROMETER) MINIMUM.
UNDERPLATE: NICKEL (Ni) OVER ENTIRE CONTACT.

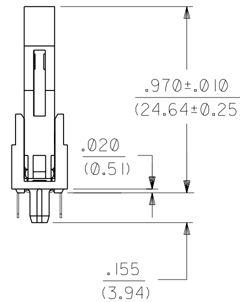
NOTE FOR LEAD FREE CONVERSION:

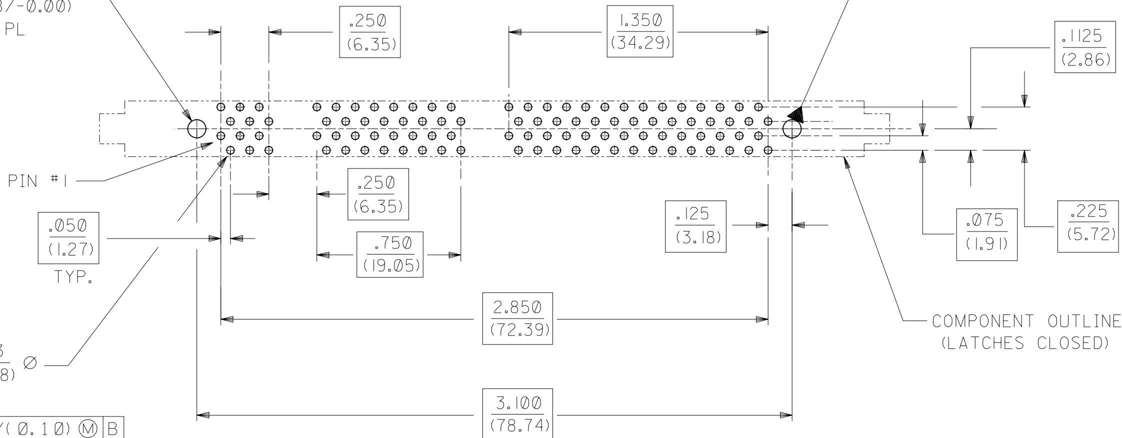
THE PRIMARY SHIPPING CARTON WILL BE LABELED "COMPLIANT TO RoHS DIRECTIVE 2002/95/EC AND ELV ANNEX II OF DIRECTIVE 2000/53/EC". CARTONS WITHOUT THIS LABEL MAY CONTAIN PRODUCT WITH LEAD.



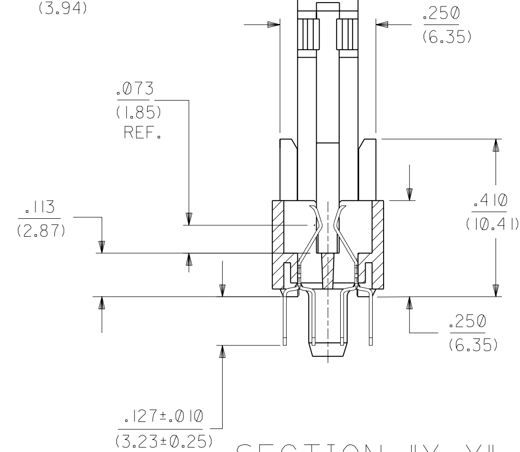


71251-5101 SHOWN





RECOMMENDED
P.C. BOARD HOLE PATTERN
(CONNECTOR SIDE)



SECTION "X-X"

SCALE 4:1

LTR.	REVISIONS
C1	ADD LEAD FREE NOTE ECN# UCP2004-1732 DMORGAN 04/03/09
C	CHANGE PLATING ECN# UDT2002-0772 DMORGAN 02/01/22
B	CHG Sn-Pb THICKNESS ECN# UDT1999-0454 DMORGAN 99/08/09
A1	REVISED PER ECR# U80435 97-8-8 LAURX
A	REVISED PER ECR# U70042 96-7-23 LAURX
2	REVISED PER ECR# U61257 4-10-96 JCL
1	X-RELEASE PER ECR# U61175 3-26-96 JCL

MFG.	SH.	REV.
	2	A1
	1	C1

REVISE ONLY ON CAD SYSTEM

DIMENSIONS SHOWN (METRIC) INCH

UNLESS OTHERWISE SPECIFIED TOLERANCES: ANGULAR ± 1/2°

	INCH	METRIC
3 PLACE	± .005	---
2 PLACE	± ---	± 0.13
1 PLACE	---	± 0.25

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

TITLE: .050 PITCH DIMM 100 CKT MULTI-KEY SALES DRAWING

MOLEX INCORPORATED LISLE, ILL. 60532 U.S.A.

SHEET NO. 1 OF 2 | DATE 03/26/96

PART NO. SEE CHART | DRWG. NO. SDA-71251-5***

DRWG. BY JCL | CHK'D. BY DCB | APP'D. BY DCB | SCALE 2:1

FILE NAME S7125151 DGN

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DIV. CP | SIZE C

PART NUMBER	DESCRIPTION	FUNCTION KEY	VOLTAGE KEY	DIM. "H"
71251-5101	3.3 VOLT UNBUFFERED	OFFSET RIGHT	CENTER	1.011 (25.68)
71251-5102	5.0 VOLT UNBUFFERED	OFFSET RIGHT	OFFSET LEFT	1.011 (25.68)

NOTES:

1. STRAIGHTNESS OF MODULE APPLIES TO THE AREA FROM THE BOTTOM OF THE CARD UP .157/(4.00).
2. IF TIE BARS ARE ATTACHED TO PADS, THE TIE BAR SHOULD BE ON AN INTERNAL LAYER, SO THAT THE REMNANT CANNOT CAUSE DAMAGE TO THE CONTACTS.

.118 (3.00) MIN.
.086 (2.175)
FULL R. TYP.
⊕ .004/(0.10) Ⓛ C B A
.079±.004 (2.00±0.10)

OFFSET LEFT KEY

.118 (3.00) MIN.
.125 (3.175)
FULL R. TYP.
⊕ .004/(0.10) Ⓛ C B A
.079±.004 (2.00±0.10)

CENTERED KEY

.118 (3.00) MIN.
.164 (4.175)
FULL R. TYP.
⊕ .004/(0.10) Ⓛ C B A
.079±.004 (2.00±0.10)

OFFSET RIGHT KEY

3.550 (90.17) ⊕ .006\(0.15) Ⓜ C B A
"H"
.118 (3.00) MIN.
.157±.004 (4.00±0.10) ⊕ .004/(0.10) Ⓜ C AⓂ B
FUNCTION KEY
℄ OF A
FULL RAD.
VOLTAGE KEY
COMPONENT AREA
MIN. .157 (4.00)
1.000 (25.40)
.701 (17.80)
B
PIN #1
PIN #51 (BACK)
.175 (4.445)
TYP. .250 (6.35)
.098±.008 (2.50±0.20)
.750 (19.05)
1.350 (34.29)
.008±.006 (0.20±0.15)
.250 (6.35)
.079 (2.00) TYP. REF.
.039±.002 (1.00±0.05)
⊕ .004/(0.10) Ⓛ C B A
2.850 (72.39)
A
(OUTSIDE EDGE OF END PADS)

C
.050±.004 (1.27±0.10)
— .011/(0.27) Ⓜ
SEE NOTE 1.

RECOMMENDED MODULE LAYOUT
100 CKT 3.3V UNBUFFERED

LTR.	REVISIONS
A1	SEE SHEET 1
A	SEE SHEET 1
2	SEE SHEET 1
1	SEE SHEET 1

MFG. SH. REV. LTR. REVISIONS

REVISE ONLY ON CAD SYSTEM

DIMENSIONS SHOWN (METRIC) INCH
UNLESS OTHERWISE SPECIFIED TOLERANCES: ANGULAR ± 1/2°

	INCH	METRIC
3 PLACE	± .005	---
2 PLACE	± .01	± 0.13
1 PLACE	---	± 0.25

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

TITLE .050 PITCH DIMM 100 CKT MULTI-KEY SALES DRAWING

MOLEX INCORPORATED LISLE, ILL. 60532 U.S.A.
SHEET NO. 2 DATE 03/26/96
PART NO. SEE CHART DRWG. NO. SDA-71251-5***
DRWG. BY JCL CHK'D. BY DCB
APP'D. BY DCB SCALE 2:1
FILE NAME S7125152 DGN

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DIV. CP SIZE C